

International
IR Rectifier

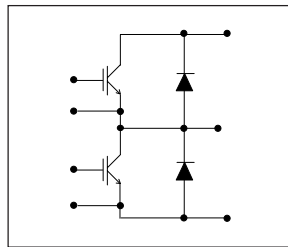
40MT120UHA
40MT120UHTA

"HALF-BRIDGE" IGBT MTP

UltraFast NPT IGBT

Features

- UltraFast Non Punch Through (NPT) Technology
- Positive $V_{CE(ON)}$ Temperature Coefficient
- 10 μ s Short Circuit Capability
- HEXFRED™ Antiparallel Diodes with UltraSoft Reverse Recovery and Low V_F
- Square RBSOA
- Al₂O₃ DBC
- Optional SMD Thermistor (NTC)
- Very Low Stray Inductance Design for High Speed Operation

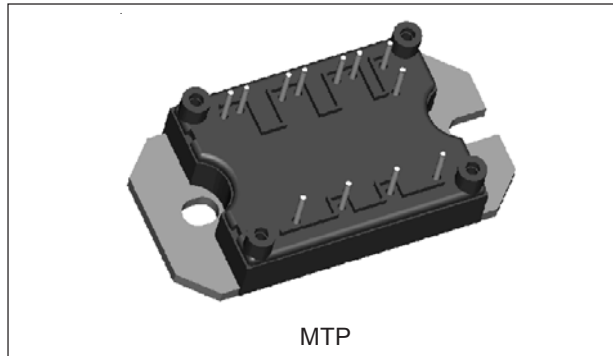


$$V_{CES} = 1200V$$

$$I_C = 80A$$

Benefits

- Optimized for Welding, UPS and SMPS Applications
- Rugged with UltraFast Performance
- Benchmark Efficiency above 20KHz
- Outstanding ZVS and Hard Switching Operation
- Low EMI, requires Less Snubbing
- Excellent Current Sharing in Parallel Operation
- Direct Mounting to Heatsink
- PCB Solderable Terminals
- Very Low Junction-to-Case Thermal Resistance



Absolute Maximum Ratings

Parameters	Max	Units
V_{CES} Collector-to-Emitter Breakdown Voltage	1200	V
I_C Continuous Collector Current	@ $T_C = 22^\circ\text{C}$	80
	@ $T_C = 104^\circ\text{C}$	40
I_{CM} Pulsed Collector Current	160	
I_{LM} Clamped Inductive Load Current	160	
I_F Diode Continuous Forward Current	@ $T_C = 105^\circ\text{C}$	21
I_{FM} Diode Maximum Forward Current	160	
V_{GE} Gate-to-Emitter Voltage	± 20	V
V_{ISOL} RMS Isolation Voltage, Any Terminal to Case, $t = 1$ min	2500	
P_D Maximum Power Dissipation (only IGBT)	@ $T_C = 25^\circ\text{C}$	463
	@ $T_C = 100^\circ\text{C}$	185
		W

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Parameters	Min	Typ	Max	Units	Test Conditions
$V_{(BR)CES}$ Collector-to-Emitter Breakdown Voltage	1200			V	$V_{GE} = 0V, I_C = 250\mu A$
$\Delta V_{(BR)CES}/\Delta T_J$ Temperature Coeff. of Breakdown Voltage		+1.1		V/ $^\circ\text{C}$	$V_{GE} = 0V, I_C = 3mA (25-125^\circ\text{C})$
$V_{CE(ON)}$ Collector-to-Emitter Saturation Voltage		3.36	3.59	V	$V_{GE} = 15V, I_C = 40A$
		4.53	4.91		$V_{GE} = 15V, I_C = 80A$
		3.88	4.10		$V_{GE} = 15V, I_C = 40A, T_J = 150^\circ\text{C}$
		5.35	5.68		$V_{GE} = 15V, I_C = 80A, T_J = 150^\circ\text{C}$
$V_{GE(th)}$ Gate Threshold Voltage	4		6	V	$V_{CE} = V_{GE}, I_C = 500\mu A$
$\Delta V_{GE(th)}/\Delta T_J$ Temperature Coeff. of Threshold Voltage		-12		mV/ $^\circ\text{C}$	$V_{CE} = V_{GE}, I_C = 1mA (25-125^\circ\text{C})$
g_{fe} Transconductance		35		S	$V_{CE} = 50V, I_C = 40A, PW = 80\mu s$
I_{CES} Zero Gate Voltage Collector Current			250	μA	$V_{GE} = 0V, V_{CE} = 1200V, T_J = 25^\circ\text{C}$
		0.4	1.0	mA	$V_{GE} = 0V, V_{CE} = 1200V, T_J = 125^\circ\text{C}$
		0.2	10		$V_{GE} = 0V, V_{CE} = 1200V, T_J = 150^\circ\text{C}$
I_{GES} Gate-to-Emitter Leakage Current			± 250	nA	$V_{GE} = \pm 20V$

Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Parameters	Min	Typ	Max	Units	Test Conditions
Q_g Total Gate Charge (turn-on)		399	599	nC	$I_C = 40A$
Q_{ge} Gate-Emitter Charge (turn-on)		43	65		$V_{CC} = 600V$
Q_{gc} Gate-Collector Charge (turn-on)		187	281		$V_{GE} = 15V$
E_{on} Turn-On Switching Loss		1142	1713	μJ	$V_{CC} = 600V, I_C = 40A$
E_{off} Turn-Off Switching Loss		1345	2018		$V_{GE} = 15V, R_g = 5\Omega, L = 200\mu H$
E_{tot} Total Switching Loss		2487	3731		$T_J = 25^\circ\text{C}$, Energy losses include tail and diode reverse recovery
E_{on} Turn-On Switching Loss		1598	2397	μJ	$V_{CC} = 600V, I_C = 40A$
E_{off} Turn-Off Switching Loss		1618	2427		$V_{GE} = 15V, R_g = 5\Omega, L = 200\mu H$
E_{tot} Total Switching Loss		3216	4824		$T_J = 125^\circ\text{C}$, Energy losses include tail and diode reverse recovery
C_{ies} Input Capacitance		5521	8282	pF	$V_{GE} = 0V$
C_{oes} Output Capacitance		380	570		$V_{CC} = 30V$
C_{res} Reverse Transfer Capacitance		171	257		$f = 1.0\text{ MHz}$
RBSOA Reverse Bias Safe Operating Area	full square				$T_J = 150^\circ\text{C}, I_C = 160A$ $V_{CC} = 1000V, V_p = 1200V$ $R_g = 5\Omega, V_{GE} = +15V \text{ to } 0V$
SCSOA Short Circuit Safe Operating Area	10			μs	$T_J = 150^\circ\text{C}$ $V_{CC} = 900V, V_p = 1200V$ $R_g = 5\Omega, V_{GE} = +15V \text{ to } 0V$

Diode Characteristics @ T_J = 25°C (unless otherwise specified)

Parameters	Min	Typ	Max	Units	Test Conditions
V _{FM} Diode Forward Voltage Drop		2.98	3.38	V	I _C = 40A
		3.90	4.41		I _C = 80A
		3.08	3.39		I _C = 40A, T _J = 125°C
		4.29	4.72		I _C = 80A, T _J = 125°C
		3.12	3.42		I _C = 40A, T _J = 150°C
E _{rec} Reverse Recovery Energy of the Diode		574	861	μJ	V _{GE} = 15V, R _g = 5Ω, L = 200μH
t _{rr} Diode Reverse Recovery Time		120	180	ns	V _{CC} = 600V, I _C = 40A
I _{rr} Peak Reverse Recovery Current		43	65	A	T _J = 125°C

Thermistor Specifications (40MT120UHTA only)

Parameters	Min	Typ	Max	Units	Test Conditions
R ₀ ⁽¹⁾ Resistance		30		kΩ	T ₀ = 25°C
β ⁽¹⁾⁽²⁾ Sensitivity index of the thermistor material		4000		K	T ₀ = 25°C T ₁ = 85°C

⁽¹⁾ T₀, T₁ are thermistor's temperatures

$$\frac{R_0}{R_1} = \exp \left[\beta \left(\frac{1}{T_0} - \frac{1}{T_1} \right) \right], \text{ Temperatures in Kelvin}$$

Thermal- Mechanical Specifications

Parameters	Min	Typ	Max	Units
T _J Operating Junction Temperature Range	- 40		150	°C
T _{STG} Storage Temperature Range	- 40		125	
R _{thJC} Junction-to-Case	IGBT		0.29	°C/ W
	Diode		0.61	
R _{thCS} Case-to-Sink (Heatsink Compound Thermal Conductivity = 1 W/mK)	Module	0.06		
Clearance (external shortest distance in air between two terminals)	5.5			mm
Creepage (shortest distance along external surface of the insulating material between 2 terminals)	8			
T Mounting torque to heatsink (3)	3 ± 10%			Nm
Wt Weight	66			g (oz)

(3) A mounting compound is recommended and the torque should be checked after 3 hours to allow for the spread of the compound. Lubricated threads

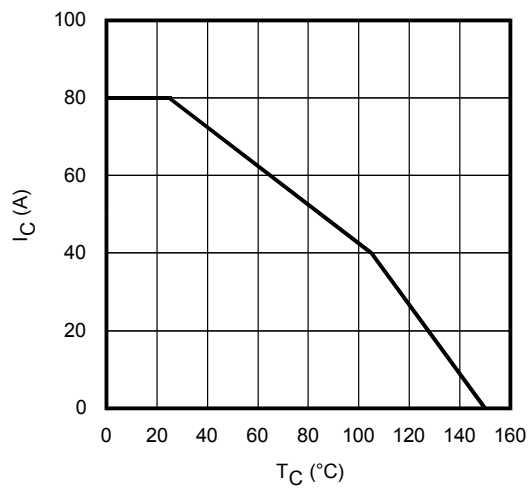


Fig. 1 - Maximum DC Collector Current vs. Case Temperature

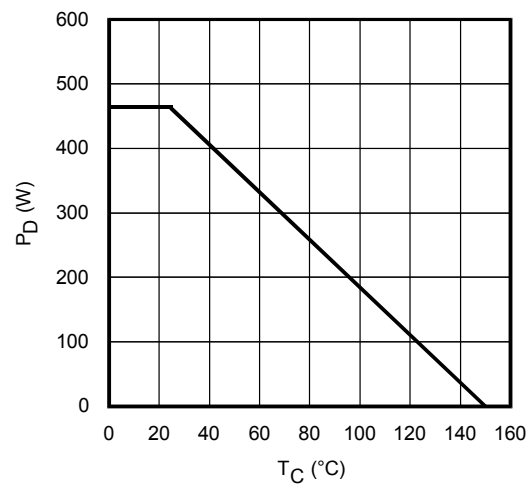


Fig. 2 - Power Dissipation vs. Case Temperature

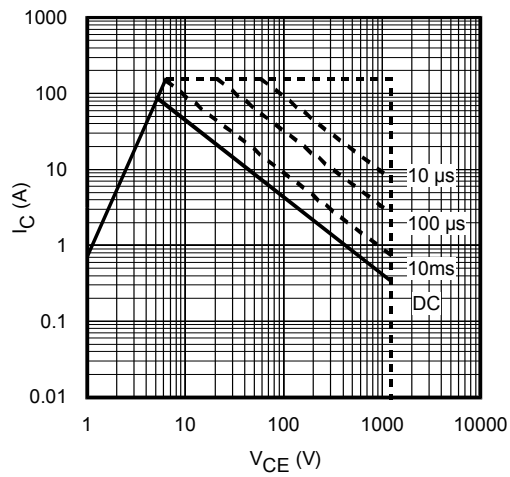


Fig. 3 - Forward SOA
 $T_C = 25^\circ\text{C}$; $T_J \leq 150^\circ\text{C}$

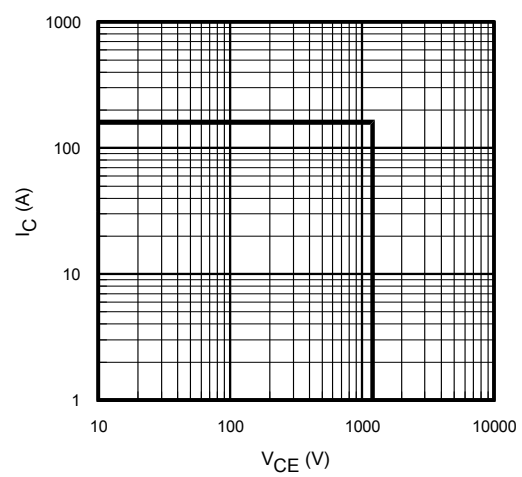


Fig. 4 - Reverse Bias SOA
 $T_J = 150^\circ\text{C}$; $V_{GE} = 15\text{V}$

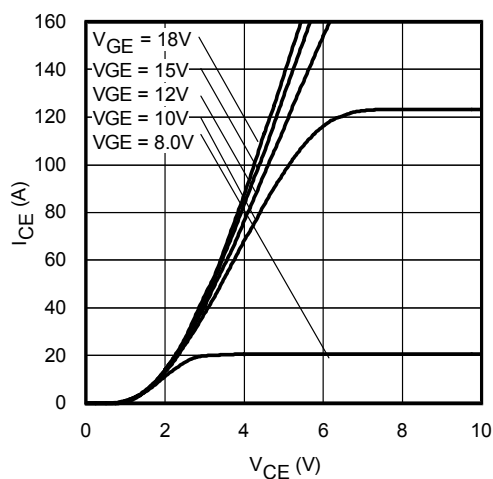


Fig. 5 - Typ. IGBT Output Characteristics
 $T_J = -40^{\circ}\text{C}$; $t_p = 80\mu\text{s}$

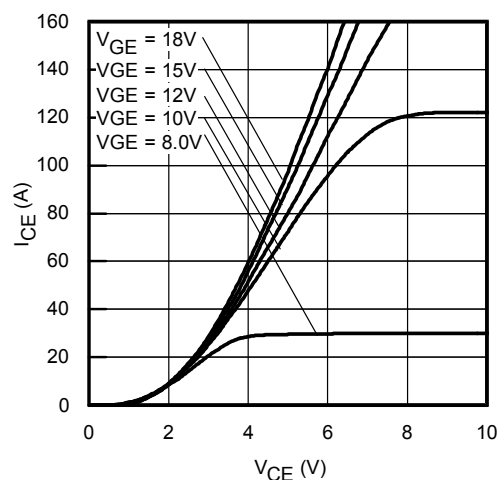


Fig. 6 - Typ. IGBT Output Characteristics
 $T_J = 25^{\circ}\text{C}$; $t_p = 80\mu\text{s}$

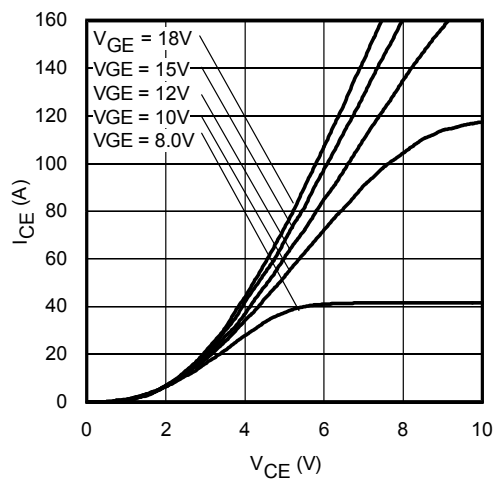


Fig. 7 - Typ. IGBT Output Characteristics
 $T_J = 125^{\circ}\text{C}$; $t_p = 80\mu\text{s}$

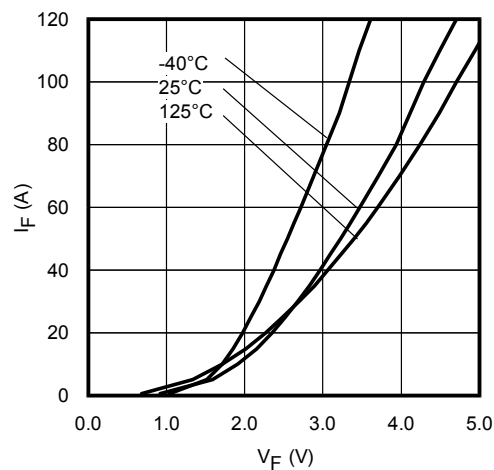


Fig. 8 - Typ. Diode Forward Characteristics
 $t_p = 80\mu\text{s}$

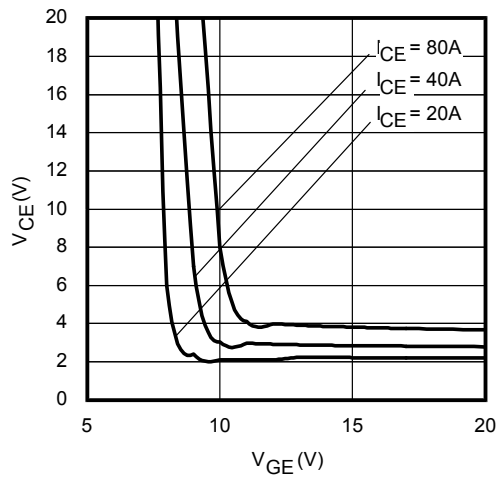


Fig. 9 - Typical V_{CE} vs. V_{GE}
 $T_J = -40^\circ\text{C}$

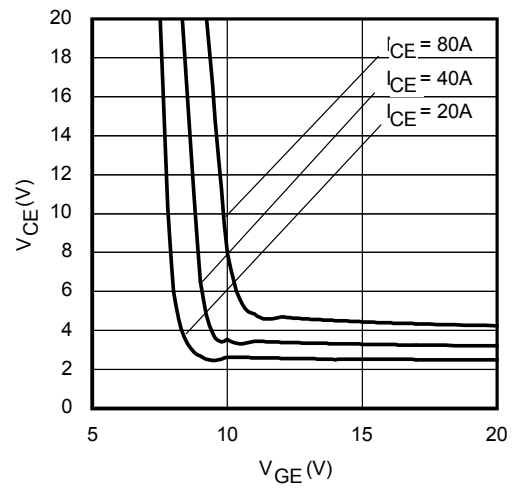


Fig. 10 - Typical V_{CE} vs. V_{GE}
 $T_J = 25^\circ\text{C}$

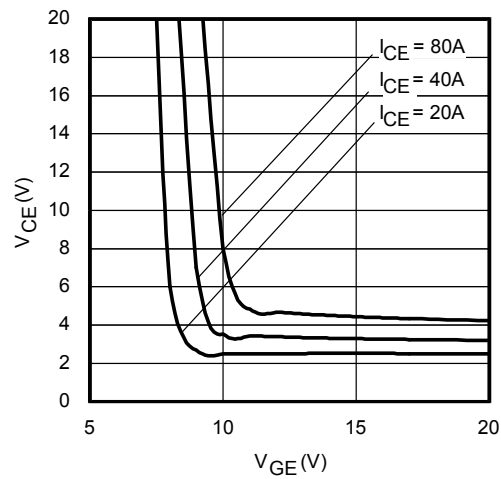


Fig. 11 - Typical V_{CE} vs. V_{GE}
 $T_J = 125^\circ\text{C}$

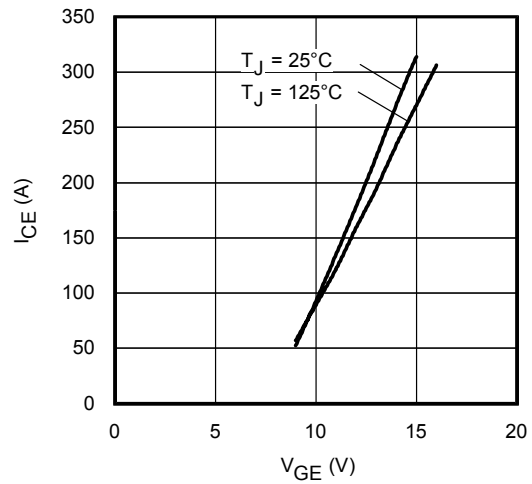


Fig. 12 - Typ. Transfer Characteristics
 $V_{CE} = 50\text{V}$; $t_p = 10\mu\text{s}$

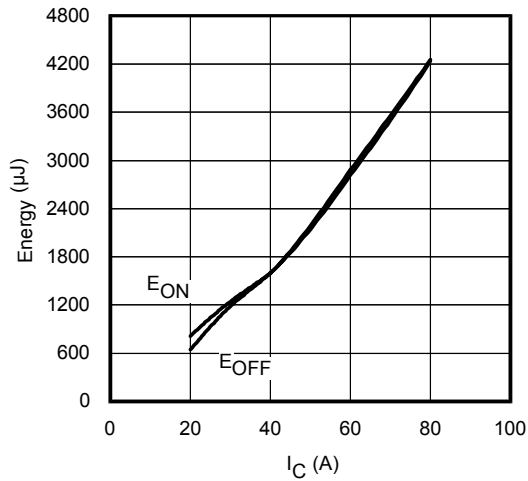


Fig. 13 - Typ. Energy Loss vs. I_C
 $T_J = 125^\circ\text{C}$; $L=250\mu\text{H}$; $V_{CE}=400\text{V}$
 $R_G=5\Omega$; $V_{GE}=15\text{V}$

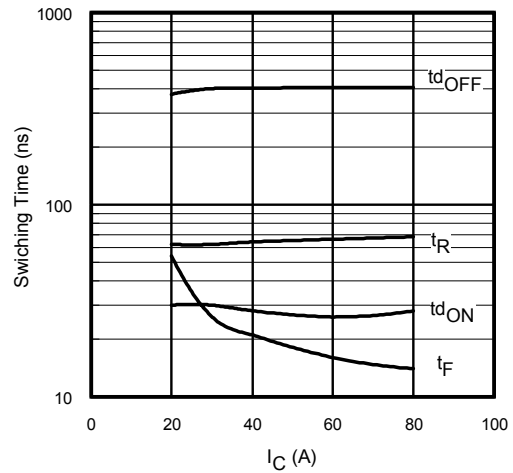


Fig. 14 - Typ. Switching Time vs. I_C
 $T_J = 125^\circ\text{C}$; $L=250\mu\text{H}$; $V_{CE}=400\text{V}$
 $R_G=5\Omega$; $V_{GE}=15\text{V}$

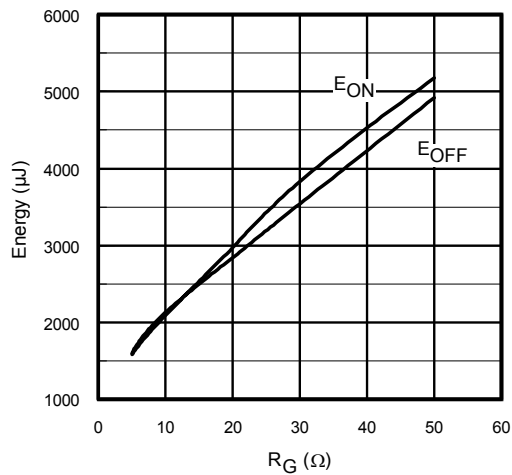


Fig. 15 - Typ. Energy Loss vs. R_G
 $T_J = 150^\circ\text{C}$; $L=250\mu\text{H}$; $V_{CE}=600\text{V}$
 $I_{CE}=40\text{A}$; $V_{GE}=15\text{V}$

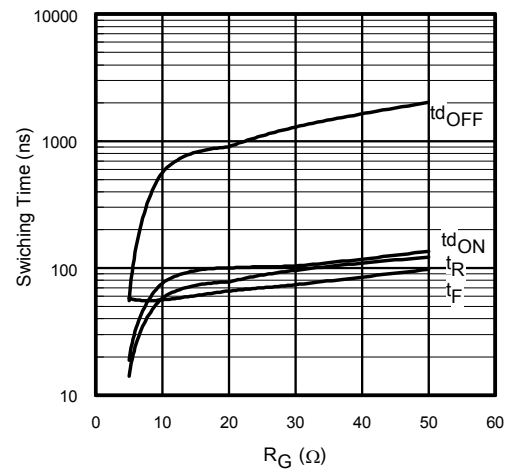


Fig. 16 - Typ. Switching Time vs. R_G
 $T_J = 150^\circ\text{C}$; $L=250\mu\text{H}$; $V_{CE}=600\text{V}$
 $I_{CE}=40\text{A}$; $V_{GE}=15\text{V}$

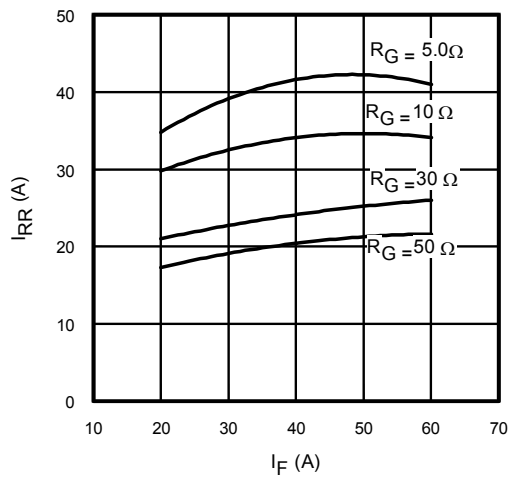


Fig. 17 - Typical Diode I_{RR} vs. I_F
 $T_J = 125^\circ\text{C}$

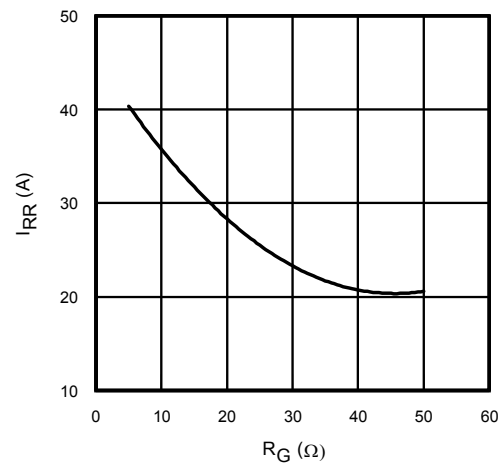


Fig. 18 - Typical Diode I_{RR} vs. R_G
 $T_J = 125^\circ\text{C}; I_F = 40\text{A}$

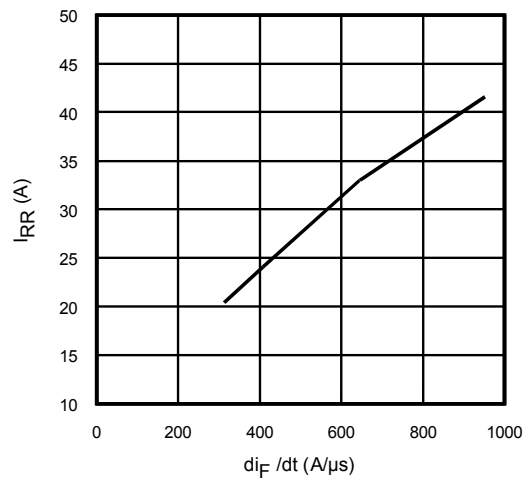


Fig. 19 - Typical Diode I_{RR} vs. di_F/dt
 $V_{CC} = 600\text{V}; V_{GE} = 15\text{V};$
 $I_{CE} = 40\text{A}; T_J = 125^\circ\text{C}$

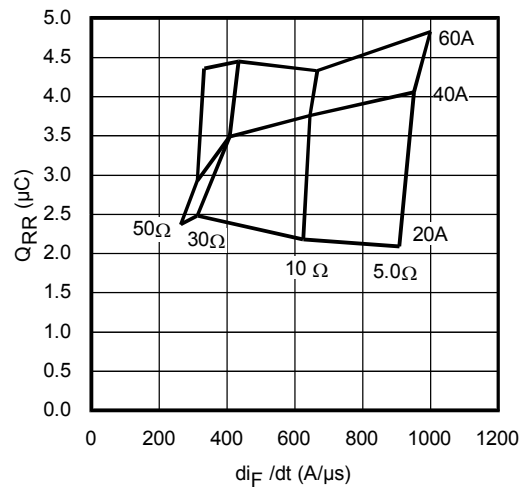


Fig. 20 - Typical Diode Q_{RR}
 $V_{CC} = 600\text{V}; V_{GE} = 15\text{V}; T_J = 125^\circ\text{C}$

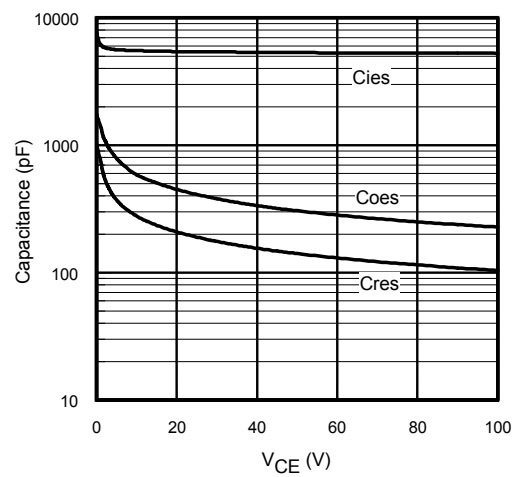


Fig. 21- Typ. Capacitance vs. V_{CE}
 $V_{GE} = 0V$; $f = 1MHz$

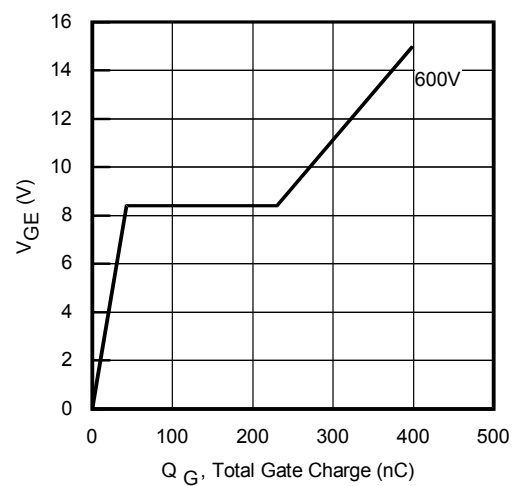


Fig. 22 - Typical Gate Charge vs. V_{GE}
 $I_{CE} = 5.0A$; $L = 600\mu H$

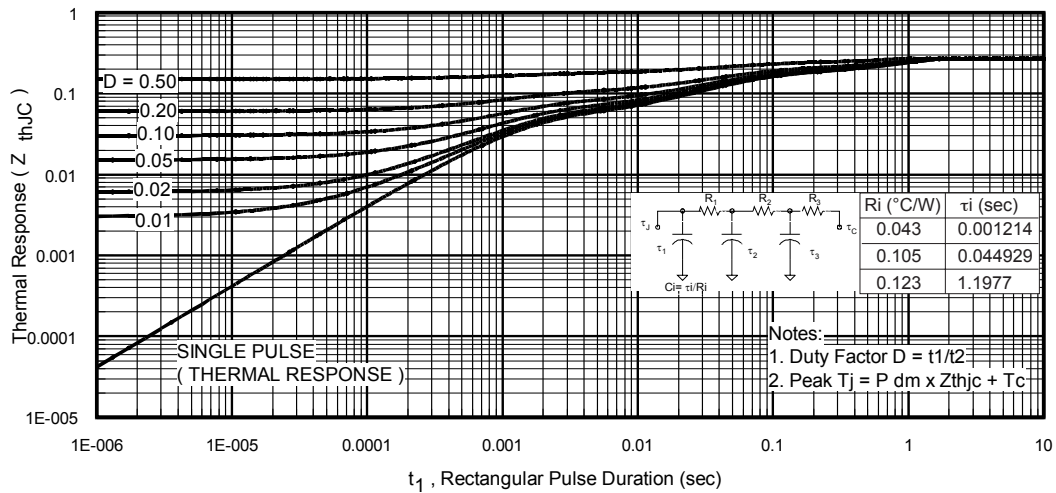


Fig 23. Maximum Transient Thermal Impedance, Junction-to-Case (IGBT)

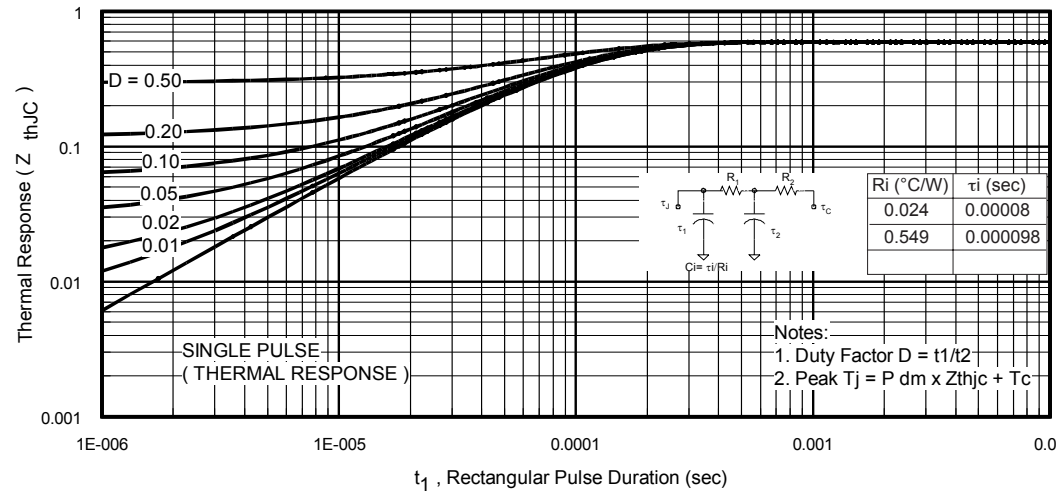


Fig 24. Maximum Transient Thermal Impedance, Junction-to-Case (DIODE)

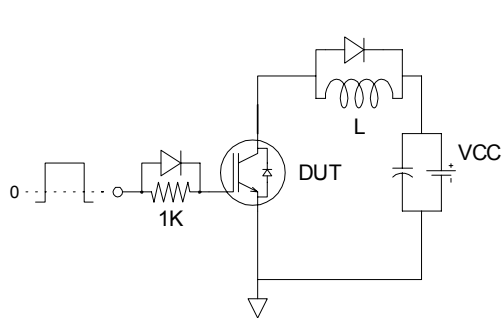


Fig. CT.1 - Gate Charge Circuit (turn-off)

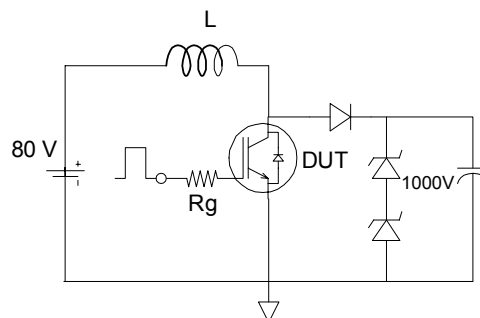


Fig. CT.2 - RBSOA Circuit

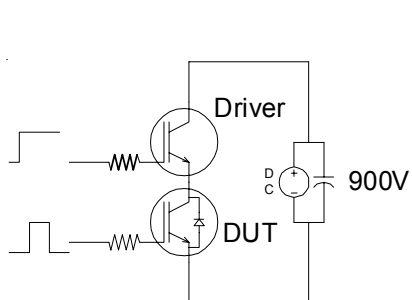


Fig. CT.3 - S.C. SOA Circuit

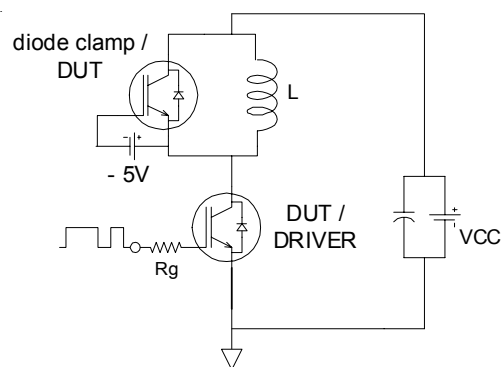
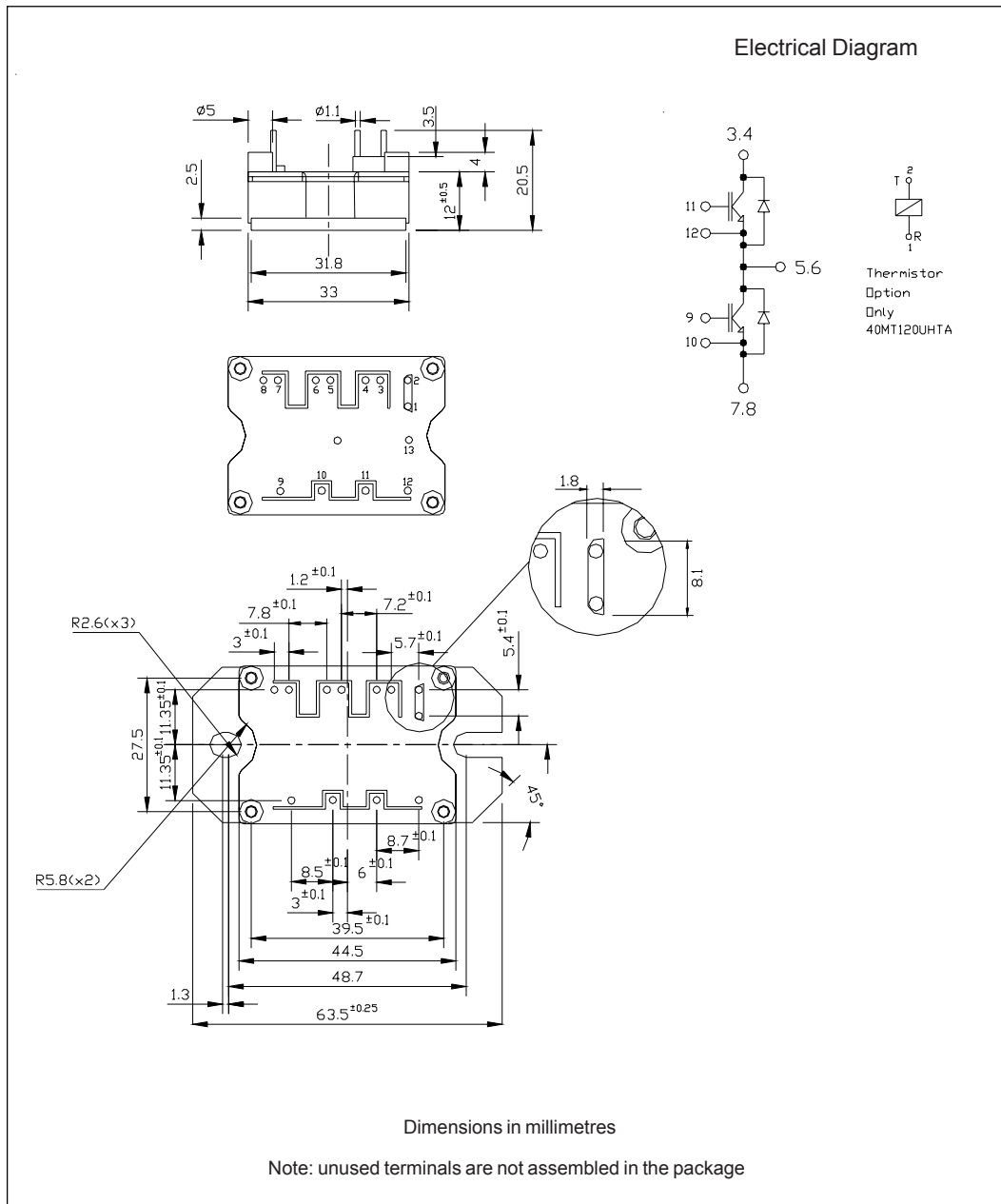


Fig. CT.4 - Switching Loss Circuit

Outline Table



Ordering Information Table

Device Code

40	MT	120	U	H	T	A
1	2	3	4	5	6	7

1	-	Current rating	(40 = 40A)
2	-	Essential Part Number	
3	-	Voltage code	(120 = 1200V)
4	-	Speed/ Type	(U = Ultra Fast IGBT)
5	-	Circuit Configuration	(H = Half Bridge)
6	-	Special Option	
		• none =	no special option
		• T =	Thermistor
7	-	A =	Al ₂ O ₃ DBC Substrate

Data and specifications subject to change without notice.
This product has been designed and qualified for Industrial Level.
Qualification Standards can be found on IR's Web site.

International
IR Rectifier

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